

PATENT

S/N 09/483,881

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

O I P E
JUL 26 2004
S C G
PATENT & TRADEMARK OFFICE
Applicant:
Serial No.:
Filed:
Title:

Kie Y. Ahn et al.
09/483,881
January 18, 2000
SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Examiner: Ha T. Nguyen

Group Art Unit: 2812

Docket: 303.672US1

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

| <u>Serial/Patent No.</u> | <u>Filing Date</u> | <u>Attorney Docket</u> | <u>Title</u> |
|--------------------------|--------------------|------------------------|--|
| 09/854540 | May 14, 2001 | 1303.013US1 | COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY |
| 10/842042 | May 7, 2004 | 303.618US3 | METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS |
| 10/854552 | May 26, 2004 | 303.664US5 | STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION |
| 10/853490 | May 25, 2004 | 1303.016US2 | COPPER DEPOSITION TECHNOLOGY FOR ULSI METALLIZATION |

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10/842243

May 10,
2004

1303.013US2

COPPER DUAL DAMASCENE
INTERCONNECT TECHNOLOGY

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicants' Representatives,

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23 July '04

By


Timothy B. Clise
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 23 day of July, 2004.

Name

Tina Kohlert

Signature

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Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

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Due Date: September 9, 2004

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MS AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- A return postcard.
- An Amendment and Response (15 Pages).
- A Communication Concerning Related Applications (2 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: 
Atty: Timothy B. Clise
Reg. No. 40,957

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Name

Tina Kohaut

Signature

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)